

## SDM3416V

### 20V N-Channel MOSFETs

Rev 1.0

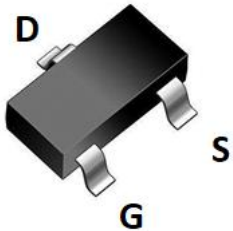
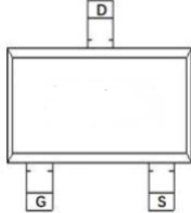
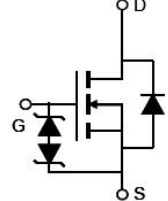
#### Feature

- ◇ Excellent  $R_{DS(ON)}$
- ◇ Low Gate Charge
- ◇ High current Capability
- ◇ Green product RoHS compliant
- ◇ ESD Protected: 4kV

#### Product Summary

$V_{DS}$	20	V
$V_{GS(th\_Typ)}$	0.7	V
$R_{DS(ON)\_Typ}$ (@ $V_{GS} = 4.5V$ )	12	m $\Omega$
$I_D$ (at $V_{GS} = 4.5V$ ) <sup>(1)</sup>	7	A

Type	Package	Marking	Outline	Media	Quantity (pcs)
SDM3416V	SOT23-3L	3416	Tape	7" Reel	3000

 <p><b>SOT23-3L top view</b></p>	 <p><b>Pin Assignment</b></p>	 <p><b>Schematic Diagram</b></p>
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#### Absolute Maximum Ratings (Rating at $T_J=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Maximum	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 10$	V
Continuous Drain Current <sup>(1)</sup>	$I_D$	$T_A=25^\circ C$	7
		$T_A=100^\circ C$	4.4
Pulsed Drain Current <sup>(2)</sup>	$I_{DM}$	28	A
Maximum Body-Diode Continuous Current	$I_S$	7	A
Avalanche Current <sup>(3)</sup>	$I_{AS}$	6.5	A
Avalanche Energy <sup>(3)</sup>	$E_{AS}$	32	mJ
Power Dissipation <sup>(4)</sup>	$P_D$	$T_A=25^\circ C$	1.3
		$T_A=100^\circ C$	0.5
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ C$

**Electrical Characteristics** (Rating at  $T_J=25^\circ\text{C}$  unless otherwise noted)

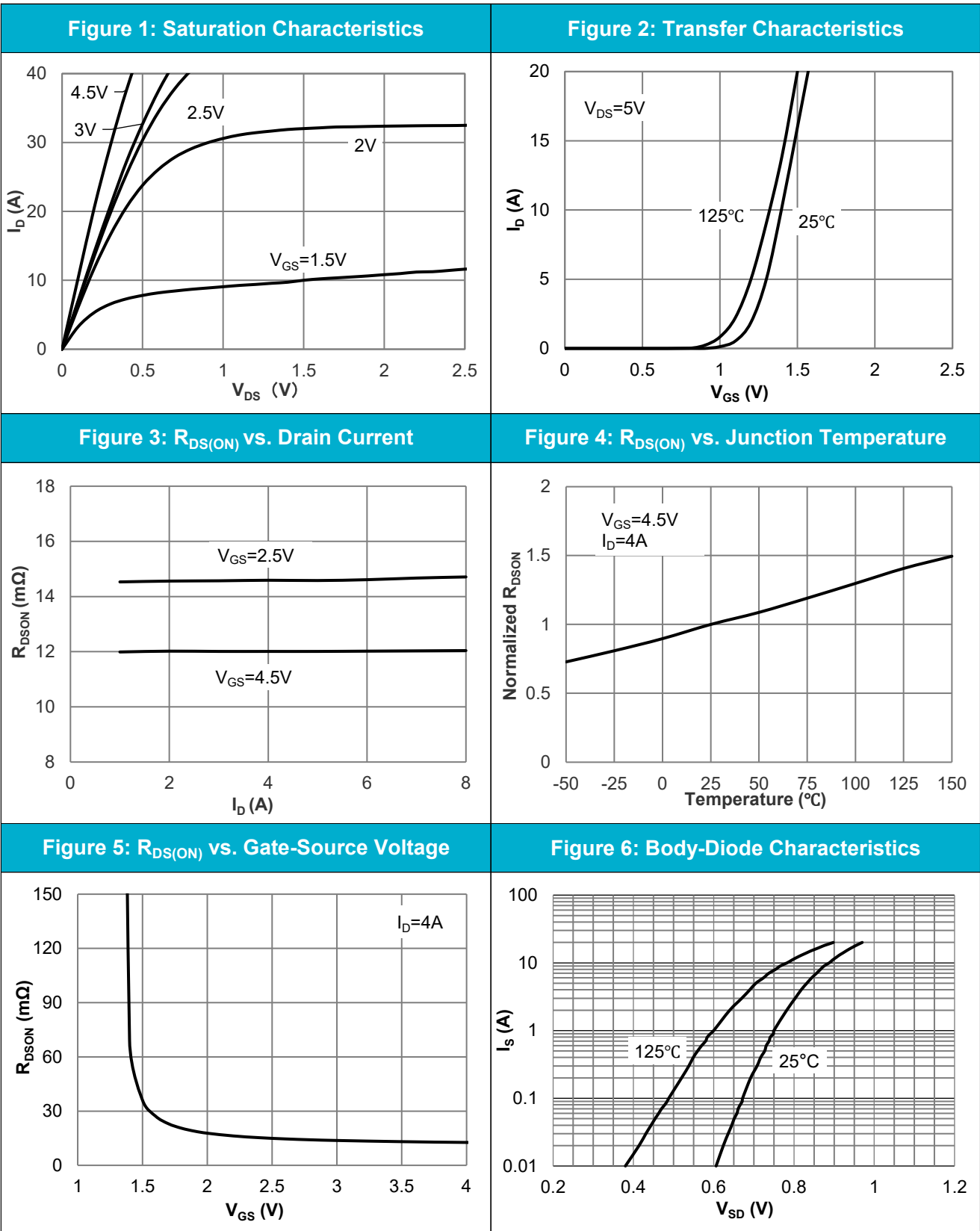
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>STATIC PARAMETERS</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}$ , $V_{GS}=0\text{V}$	20	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=20\text{V}$ , $V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$	-	-	1 5	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 10\text{V}$	-	-	$\pm 10$	$\mu\text{A}$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$	0.5	0.7	0.9	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS}=4.5\text{V}$ , $I_D=4\text{A}$	-	12	18	m $\Omega$
		$V_{GS}=2.5\text{V}$ , $I_D=3\text{A}$	-	15	22	
$g_{FS}$	Forward Transconductance	$V_{DS}=5\text{V}$ , $I_D=4\text{A}$	-	13	-	S
$V_{SD}$	Diode Forward Voltage	$I_S=4\text{A}$ , $V_{GS}=0\text{V}$	-	0.8	1	V
<b>DYNAMIC PARAMETERS</b> <sup>(5)</sup>						
$C_{iss}$	Input Capacitance	$V_{GS}=0\text{V}$ , $V_{DS}=10\text{V}$ , $f=1\text{MHz}$	-	484	-	pF
$C_{oss}$	Output Capacitance		-	116	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	71	-	pF
$R_g$	Gate Resistance	$V_{GS}=0\text{V}$ , $V_{DS}=0\text{V}$ , $f=1\text{MHz}$	-	161	-	$\Omega$
<b>SWITCHING PARAMETERS</b> <sup>(5)</sup>						
$Q_g$	Total Gate Charge	$V_{GS}=4.5\text{V}$ , $V_{DS}=10\text{V}$ , $I_D=6.5\text{A}$	-	5.7	-	nC
$Q_{gs}$	Gate Source Charge		-	0.9	-	nC
$Q_{gd}$	Gate Drain Charge		-	2.1	-	nC
$t_{D(on)}$	Turn-On Delay Time	$V_{GS}=4.5\text{V}$ , $V_{DS}=10\text{V}$ , $R_L=10\Omega$ , $R_G=6\Omega$ , $I_D=1\text{A}$	-	3.3	-	ns
$t_r$	Turn-On Rise Time		-	5.3	-	ns
$t_{D(off)}$	Turn-Off Delay Time		-	17.5	-	ns
$t_f$	Turn-Off Fall Time		-	9.1	-	ns
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F=1\text{A}$ , $di/dt=100\text{A}/\mu\text{s}$	-	7.5	-	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge	$I_F=1\text{A}$ , $di/dt=100\text{A}/\mu\text{s}$	-	1.3	-	nC

**Thermal Resistances**

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JC}$	Thermal resistance from junction to case	-	-	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal resistance from junction to ambient	-	94	$^\circ\text{C}/\text{W}$

**Notes:**

1. Computed continuous current assumes the condition of  $T_{J\_Max}$  while the actual continuous depends on the thermal & electro-mechanical application board design.
2. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
3. This single-pulse measurement was taken under the following condition [ $L=0.5\text{mH}$ ,  $V_{GS}=8\text{V}$ ,  $V_{DS}=15\text{V}$ ] while its value is limited by  $T_{J\_Max}=150^\circ\text{C}$ .
4. The power dissipation  $P_D$  is based on  $T_{J\_Max}=150^\circ\text{C}$ .
5. This value is guaranteed by design hence it is not included in the production test.



Typical Electrical and Thermal Characteristics

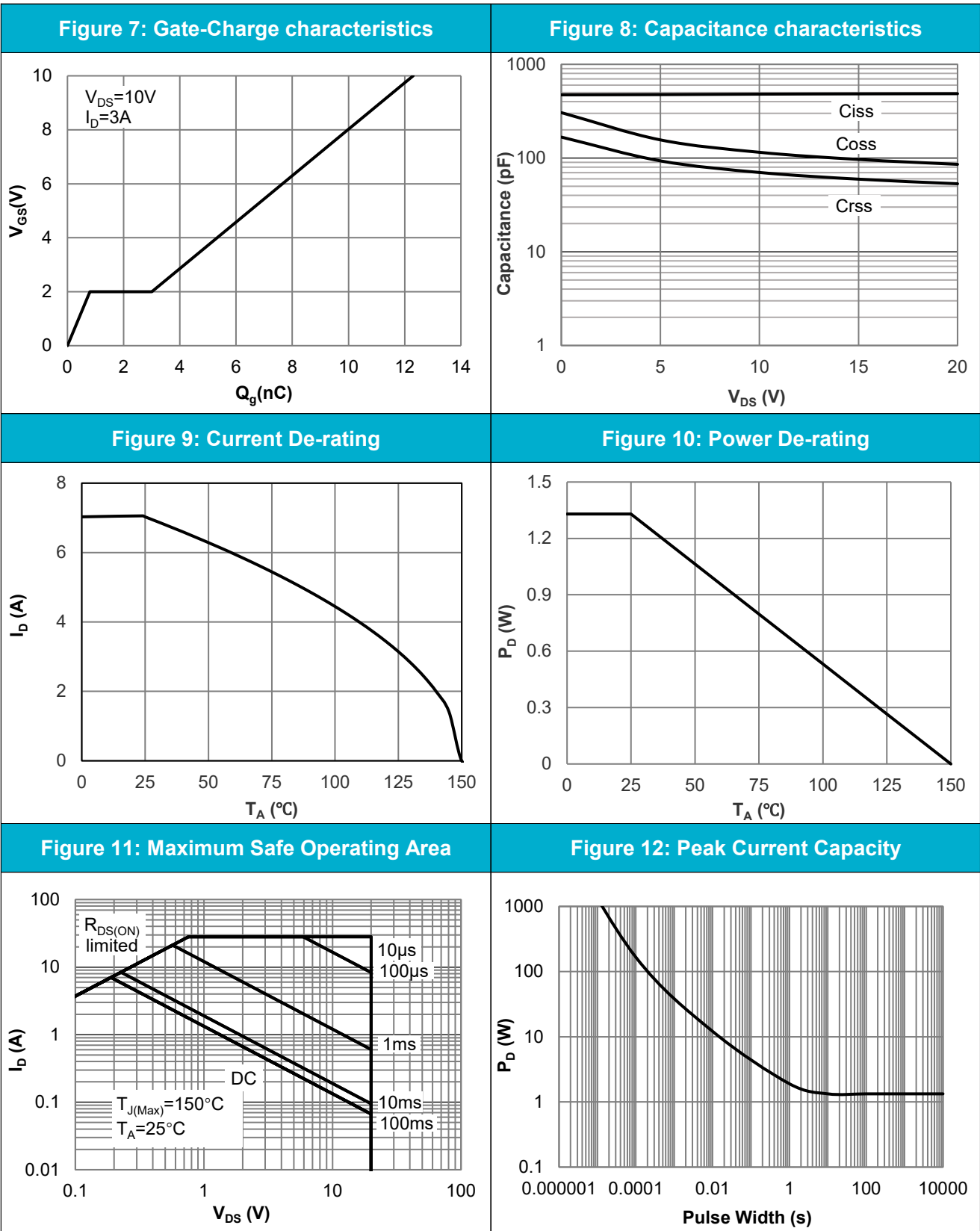
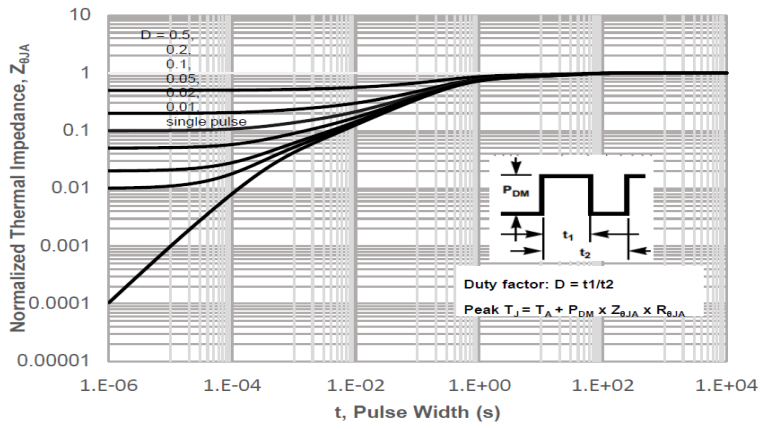


Figure 13: Normalized Maximum Transient Thermal Impedance



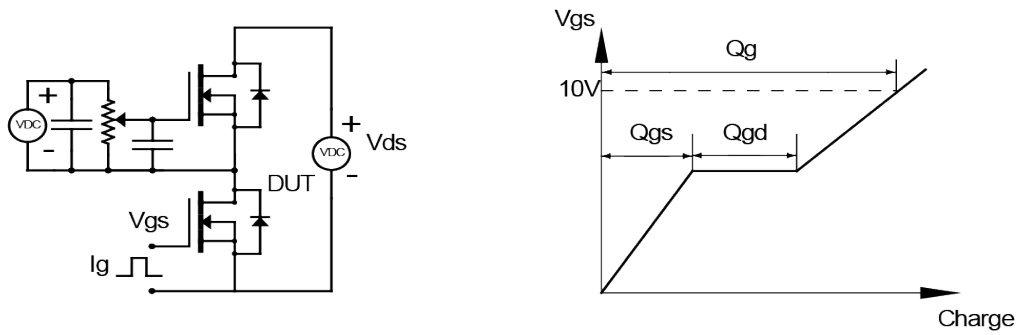


Figure1: Gate Charge Test Circuit & Waveforms

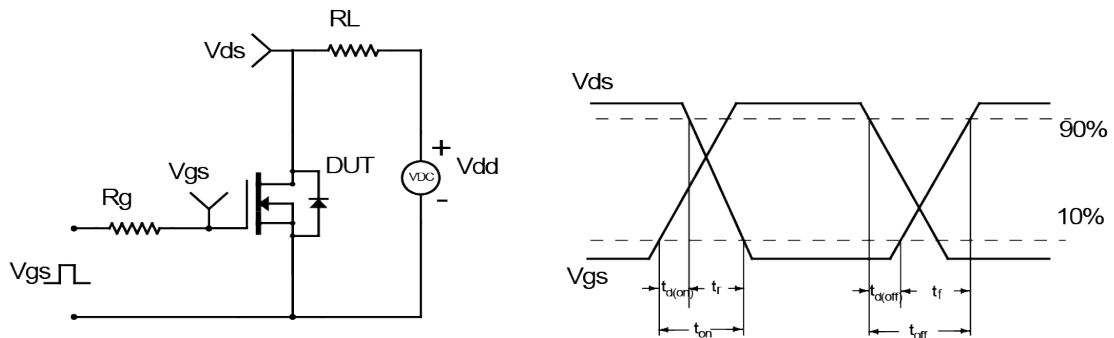


Figure2: Resistive Switching Test Circuit & Waveforms

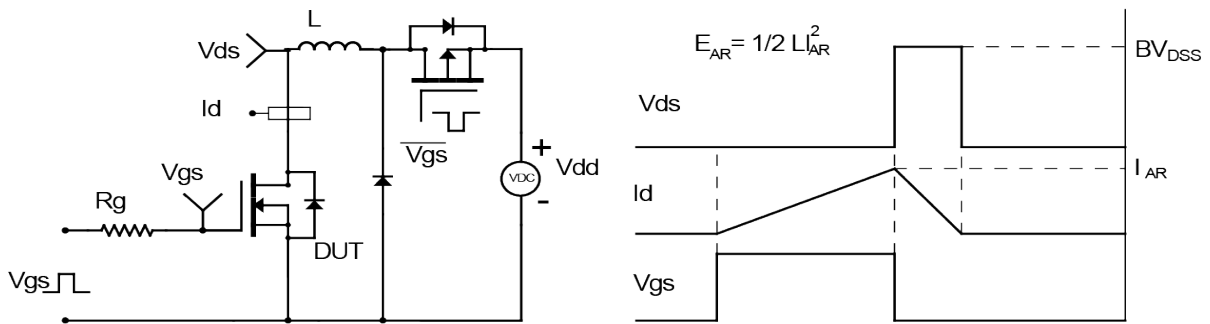


Figure3: Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

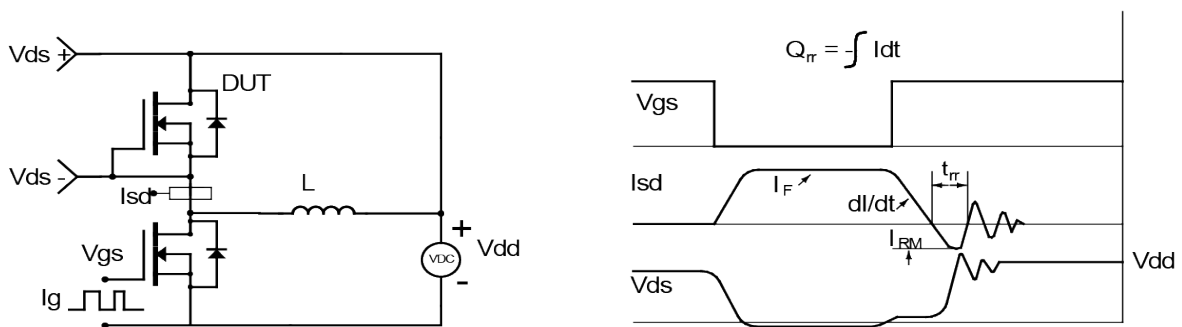
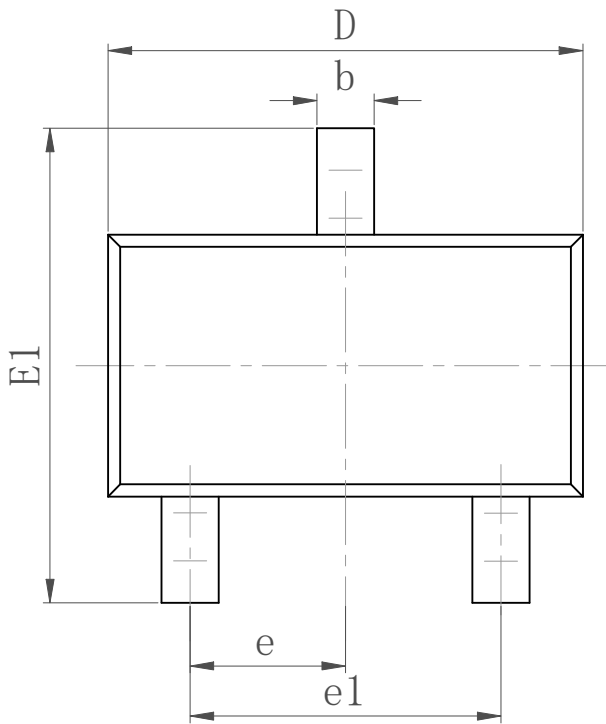
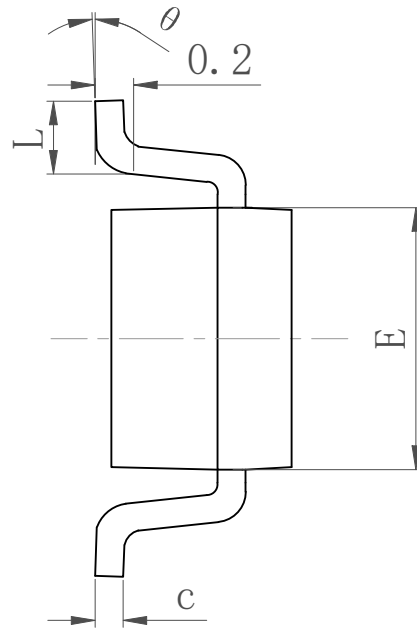


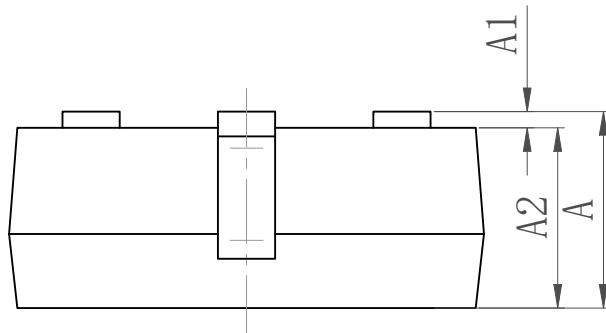
Figure4: Diode Recovery Test Circuit & Waveforms



TOP VIEW



SIDE VIEW



SIDE VIEW

SYMBOL	MILLIMETER	
	MIN	MAX
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.300	0.500
c	0.150	0.190
D	2.820	3.020
E	1.500	1.700
E1	2.650	2.950
e	0.950 (BSC)	
e1	1.800	2.000
L	0.300	0.500
θ	0°	8°